

EVLYS LTD. - POWER SEMICONDUCTORS DEVICES -
Wholesale and Retail.

Fast Thyristor Type FDT80-1600-28

Low switching losses / Low reverse recovery charge
 Distributed amplified gate for high dI_T/dt

Mean on-state current	I _{TAV}	1600 A			
Repetitive peak off-state voltage	V _{DRM}				
Repetitive peak reverse voltage	V _{RRM}	2000...2800 V			
Turn-off time	t _q	50.0, 63.0 μ s			
V _{DRM} , V _{RRM} , V	2000	2200	2400	2600	2800
Voltage code	20	22	24	26	28
T _j , °C			−60...+125		

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I _{TAV}	Mean on-state current	A	1600 1833 2715	T _c =91 °C; Double side cooled; T _c =85 °C; Double side cooled; T _c =55 °C; Double side cooled; 180° half-sine wave; 50 Hz	
I _{TRMS}	RMS on-state current	A	2512	T _c =91 °C; Double side cooled; 180° half-sine wave; 50 Hz	
I _{TSM}	Surge on-state current	kA	40.0 46.0 42.0 48.0	T _j =T _j max T _j =25 °C T _j =T _j max T _j =25 °C	180° half-sine wave; t _p =10 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =I _{FGM} ; V _G =20 V; t _{GP} =50 μ s; di _G /dt=2 A/ μ s 180° half-sine wave; t _p =8.3 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =I _{FGM} ; V _G =20 V; t _{GP} =50 μ s; di _G /dt=2 A/ μ s
I ² t	Safety factor	A ² s·10 ³	8000 10500 7300 9500	T _j =T _j max T _j =25 °C T _j =T _j max T _j =25 °C	180° half-sine wave; t _p =10 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =I _{FGM} ; V _G =20 V; t _{GP} =50 μ s; di _G /dt=2 A/ μ s 180° half-sine wave; t _p =8.3 ms; single pulse; V _D =V _R =0 V; Gate pulse: I _G =I _{FGM} ; V _G =20 V; t _{GP} =50 μ s; di _G /dt=2 A/ μ s
BLOCKING					
V _{DRM} , V _{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	2000...2800	T _{j min} < T _j <T _{j max} ; 180° half-sine wave; 50 Hz; Gate open	
V _{DSM} , V _{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	2100...2900	T _{j min} < T _j <T _{j max} ; 180° half-sine wave; single pulse; Gate open	
V _D , V _R	Direct off-state and Direct reverse voltages	V	0.6·V _{DRM} 0.6·V _{RRM}	T _j =T _j max; Gate open	

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TRIGGERING				
I_{FGM}	Peak forward gate current	A	10	
V_{RGM}	Peak reverse gate voltage	V	5	$T_j = T_{j\max}$
P_G	Gate power dissipation	W	8	$T_j = T_{j\max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1$ Hz)	A/ μ s	2500	$T_j = T_{j\max}; V_D = 0.67 \cdot V_{DRM}; I_{TM} = 5800$ A; Gate pulse: $I_G = 2$ A; $V_G = 20$ V; $t_{GP} = 50$ μ s; $di_G/dt = 2$ A/ μ s
THERMAL				
T_{stg}	Storage temperature	°C	-60...+50	
T_j	Operating junction temperature	°C	-60...+125	
MECHANICAL				
F	Mounting force	kN	40.0...50.0	
a	Acceleration	m/s ²	50	Device clamped

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions		
ON-STATE						
V_{TM}	Peak on-state voltage, max	V	2.26	$T_j = 25$ °C; $I_{TM} = 5024$ A		
$V_{T(TO)}$	On-state threshold voltage, max	V	1.360	$T_j = T_{j\max};$		
r_T	On-state slope resistance, max	$m\Omega$	0.183	$0.5 \pi I_{TAV} < I_T < 1.5 \pi I_{TAV}$		
I_H	Holding current, max	mA	1000	$T_j = 25$ °C; $V_D = 12$ V; Gate open		
BLOCKING						
I_{DRM}, I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	300	$T_j = T_{j\max};$ $V_D = V_{DRM}; V_R = V_{RRM}$		
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage ¹⁾ , min	V/ μ s	200, 320, 500, 1000, 1600, 2000, 2500	$T_j = T_{j\max};$ $V_D = 0.67 \cdot V_{DRM};$ Gate open		
TRIGGERING						
V_{GT}	Gate trigger direct voltage, max	V	3.00 3.00 1.50	$T_j = T_{j\min}$ $T_j = 25$ °C $T_j = T_{j\max}$	$V_D = 12$ V; $I_D = 3$ A; Direct gate current	
I_{GT}	Gate trigger direct current, max	mA	500 300 150	$T_j = T_{j\min}$ $T_j = 25$ °C $T_j = T_{j\max}$		
V_{GD}	Gate non-trigger direct voltage, min	V	0.35	$T_j = T_{j\max}; V_D = 0.67 \cdot V_{DRM};$		
I_{GD}	Gate non-trigger direct current, min	mA	70.00	Direct gate current		
SWITCHING						
t_{gd}	Delay time, max	μ s	1.05	$T_j = 25$ °C; $V_D = 1500$ V; $I_{TM} = I_{TAV};$ $di/dt = 200$ A/ μ s;		
t_{gt}	Turn-on time ²⁾ , max	μ s	2.50, 3.20, 4.00, 6.30	Gate pulse: $I_G = 2$ A; $V_G = 20$ V; $t_{GP} = 50$ μ s; $di_G/dt = 2$ A/ μ s		
t_q	Turn-off time ³⁾ , max	μ s	50.0, 63.0	$dv_D/dt = 50$ V/ μ s;	$T_j = T_{j\max};$ $I_{TM} = I_{TAV};$ $di_R/dt = -10$ A/ μ s; $V_R = 100$ V; $V_D = 0.67 \cdot V_{DRM}$	
			63.0, 80.0	$dv_D/dt = 200$ V/ μ s;		
Q_{rr}	Total recovered charge(linear), max	μ C	1250	$T_j = T_{j\max}; I_{TM} = 2000$ A;		
t_{rr}	Reverse recovery time, max	μ s	9.0	$di_R/dt = -50$ A/ μ s;		
I_{rrM}	Peak reverse recovery current, max	A	280	$V_R = 100$ V		

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THERMAL					
R_{thjc}	Thermal resistance, junction to case, max	$^{\circ}\text{C}/\text{W}$	0.0100	Direct current	Double side cooled
R_{thjc-A}			0.0220		Anode side cooled
R_{thjc-K}			0.0180		Cathode side cooled
R_{thck}	Thermal resistance, case to heatsink, max	$^{\circ}\text{C}/\text{W}$	0.0020	Direct current	
MECHANICAL					
W	Weight, max	g	1600		
D_s	Surface creepage distance	mm (inch)	55.13 (2.170)		
D_a	Air strike distance	mm (inch)	25.10 (0.988)		

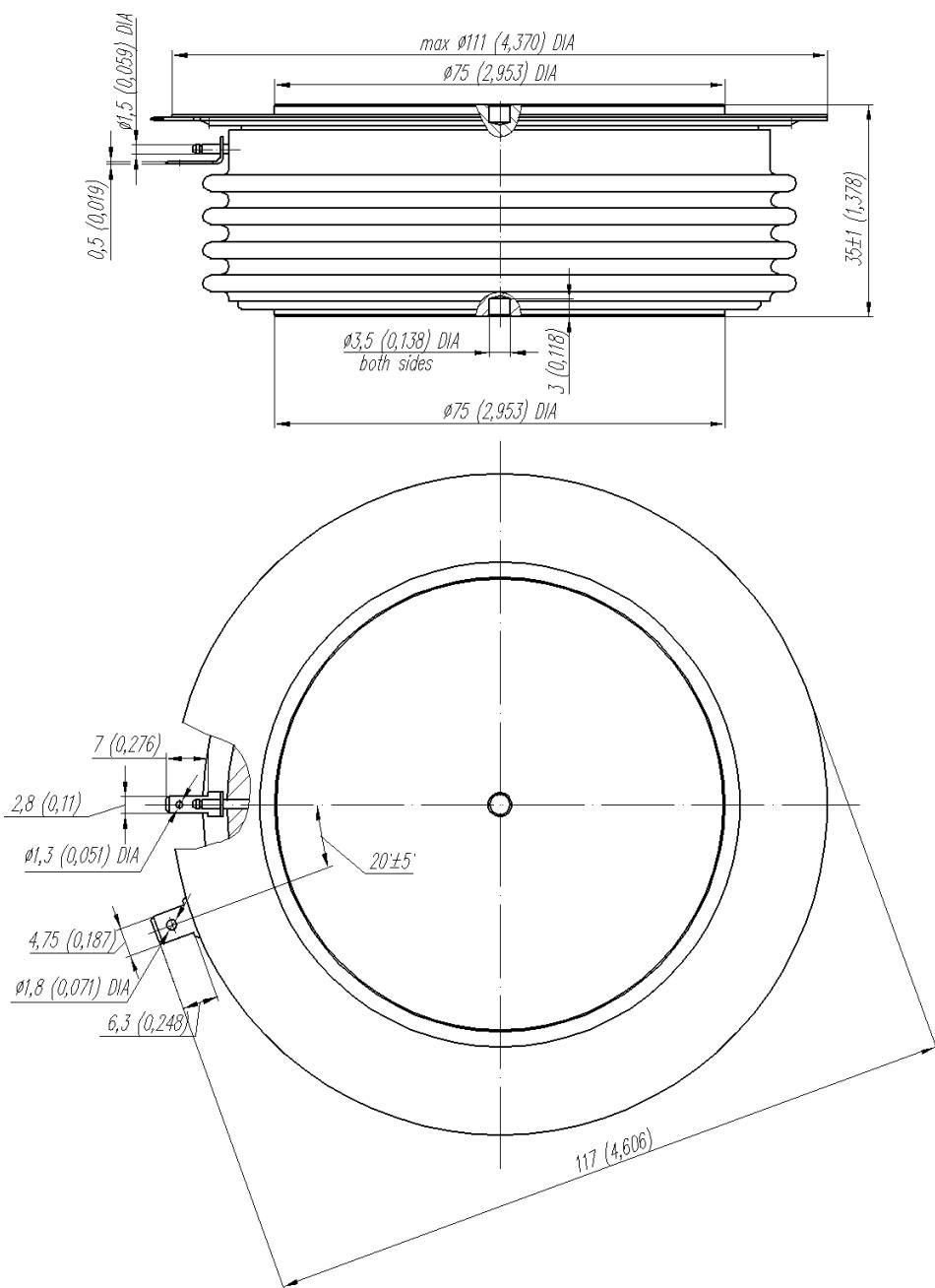
PART NUMBERING GUIDE							NOTES							
FDT	80	1600	28	7	2	4								
1	2	3	4	5	6	7								
1. FDT — Fast Inverter Disc Thyristor							1) Critical rate of rise of off-state voltage							
2. Design version							Symbol of Group	4	5	6	7	8	8,5	9
3. Mean on-state current, A							(dv _D /dt) _{crit} , V/μs	200	320	500	1000	1600	2000	2500
4. Voltage code														
5. Critical rate of rise of off-state voltage							2) Turn-on time							
6. Group of turn-off time (dv _D /dt=50 V/μs)							Symbol of group	4	3	2				
7. Group of turn-on time							t _{gt} , μs	2.50	3.20	4.00				
							3) Turn-off time (dv _D /dt=50 V/μs)							
							Symbol of group	2		1				
							t _q , μs	50.0		63.0				

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OVERALL DIMENSIONS

Package type: T.F5



All dimensions in millimeters (inches)